Integrated AC LED Solution

Acrich2 – 8.7W

SMJE-XV08W1P3

MacAdam 3-Step   UL   RoHS

Product Brief

Description

- The Acrich2 series of products are designed to be driven directly off of AC line voltage, therefore they do not need the standard converter essential for conventional general lighting products.
- The converter or driver found in most general lighting products can limit the overall life of the product, but with the Acrich2 series of products the life of the product can more closely be estimated from the LED itself. This will also allow for a much smaller form factor from an overall fixture design allowing for higher creativity in the fixture.
- The modules have a high power factor which can contribute to a higher energy savings in the end application.

Features and Benefits

- Connects directly to AC line voltage
- High Power Efficiency & Factor
- Low THD
- Long Life Time
- Simple BOM
- Miniaturization
- Lead Free Product
- RoHS Compliant

Key Applications

- Bulb Llight
- Down Light
- Factory Ceiling Light
- Industrial Light

Table 1. Product Selection (CCT)

Part No.	Vin [Vac]	P [W]	Color	CCT [K]	CRI Min.
SMJE-2V08W1P3	120	8.7	Cool	4700 – 6000	80
SMJE-3V08W1P3	220		Neutral	3700 – 4200	
			Warm	2600 – 3200	

Table 2. Product Selection (Flux)

Part No.	Vin [Vac]	P [W]	Flux Bin	Flux [lm] Min.	Flux [lm] Typ.
SMJE-2V08W1P3	120	8.7	8a	590	650
SMJE-3V08W1P3	220		8b	740	800

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Performance Characteristics

Table 3. Electro Optical Characteristics, T_a = 25ºC

Parameter	Symbol	Value			Unit	Mark
		Min.	Typ.	Max.		
Luminous Flux	Φ_V [2]	590	650	740	lm	8a
		740	800	870		8b
Correlated Color Temperature [3]	CCT	5300	5600	6000	K	B
		4700	5000	5300		C
		3700	4000	4200		E
		2900	3000	3200		G
		2600	2700	2900		H
CRI	Ra	80	-	-	-	
Input Voltage [4]	V_{in}		120		Vac	2V
			220			3V
Power Consumption	P	8.2	8.7	9.1	W	08W
Operating Frequency	f		50 / 60		Hz	
Power Factor	PF		Over 0.95		-	
Viewing Angle	$2\Theta_{1/2}$		120		deg.	

Notes :

(1) At 120Vac/220Vac, T_a = 25ºC

(2) Φ_V is the total luminous flux output measured with an integrated sphere.

(3) Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram.

(4) Operating Voltage doesn't indicate the maximum voltage which customers use but means tolerable voltage according to each country's voltage variation rate. It is recommended that the solder pad temperature should be below 70℃.

Absolute Maximum Ratings

Table 4. Absolute Maximum Ratings, T_a = 25⁰C

Parameter	Symbol	Unit	Value
Maximum Input Voltage @120Vac	V_{in}	Vac	140
Maximum Input Voltage @220Vac			264
Power Consumption	P	W	11.5
Operating Temperature	T_{opr}	⁰C	-30 ~ 85
Storage Temperature	T_{stg}	⁰C	-40 ~ 100
ESD Sensitivity	-	-	±4,000V HBM

Thermal Resistance

Part	Package Power Dissipation [W]	Maximum Junction Temperature [℃]	Rθ$_{j-s}$ [℃/W]
Acrich2 LED	SAW8KG0B Max 0.58	125	27

The Acrich2 LED has a thermal resistance of 27℃/W from junction of the LED to the

LED lead.

The maximum junction temperature of the Acrich2 LED package is 125℃, therefore the maximum

lead temperature T$_{s\_max}$ is

$T_{s\_max} = T_{j\_max} - (Rθ_{j-s} * P_d)$

$= 125℃ - (27℃/W * 0.58W) = 109.34℃$

Although this is the maximum lead temperature, it is recommended to keep the lead temperature

under 70℃.

Relative Spectral Distribution

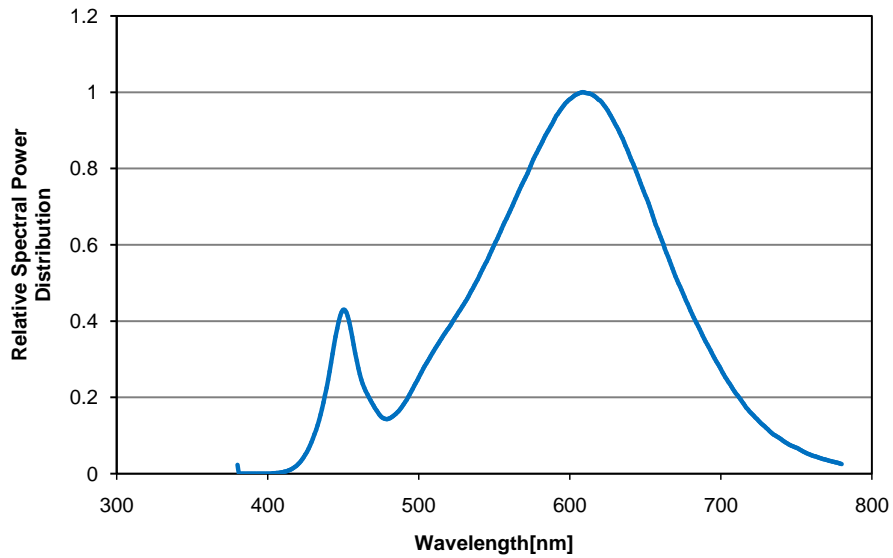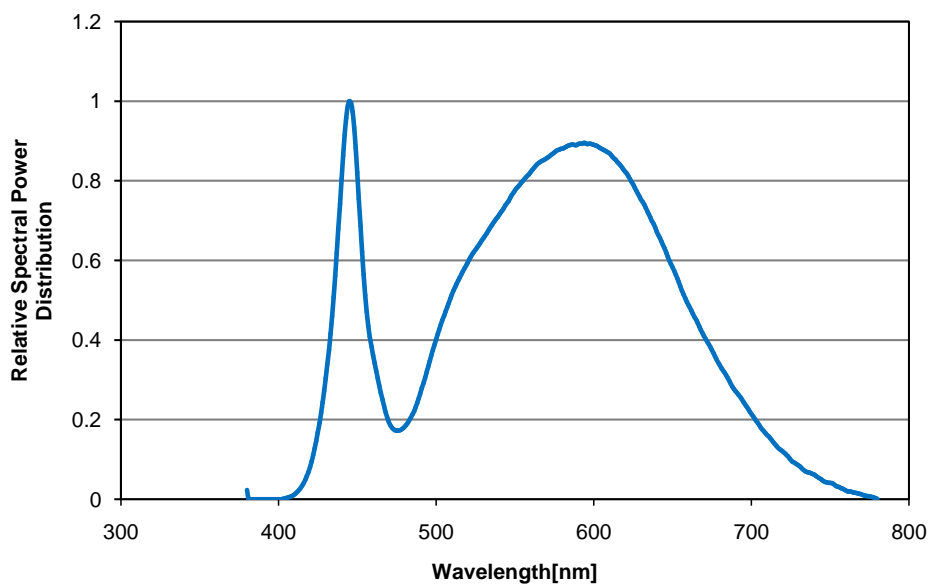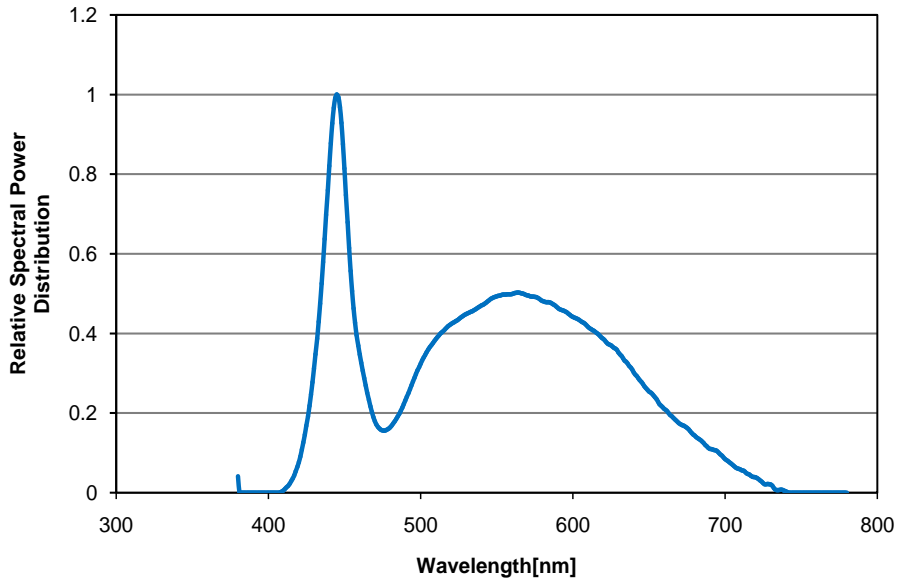**Fig 1. Relative Spectral Distribution vs. Wavelength Characteristic – G, H**

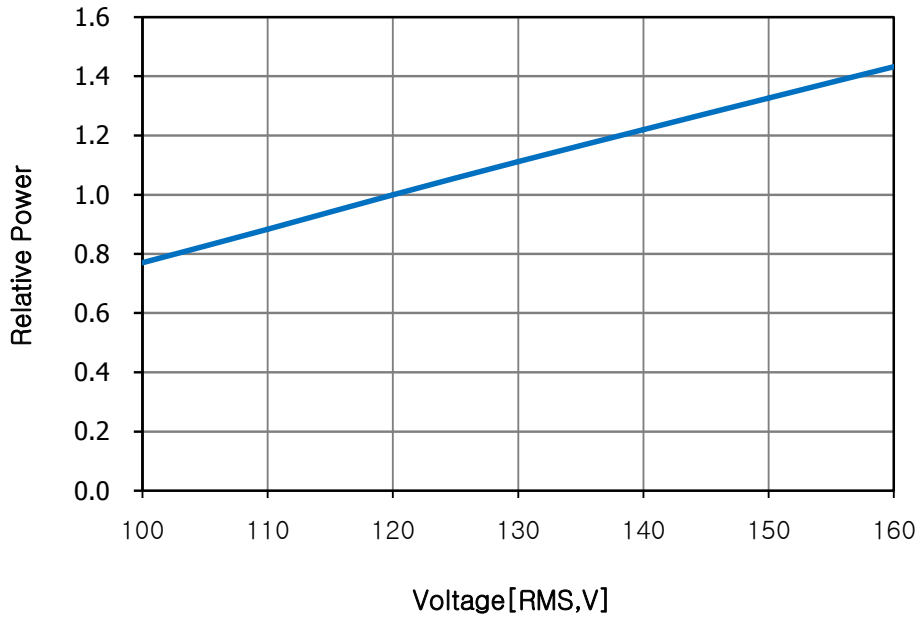**Fig 2. Relative Spectral Distribution vs. Wavelength Characteristic – E**

Relative Spectral Distribution

Fig 3. Relative Spectral Distribution vs. Wavelength Characteristic – B, C

Relative Power Distribution

Fig 4. Relative Power Distribution vs. Voltage at T$_a$=25℃, 120V

Fig 5. Relative Power Distribution vs. Voltage at T$_a$=25℃, 220V
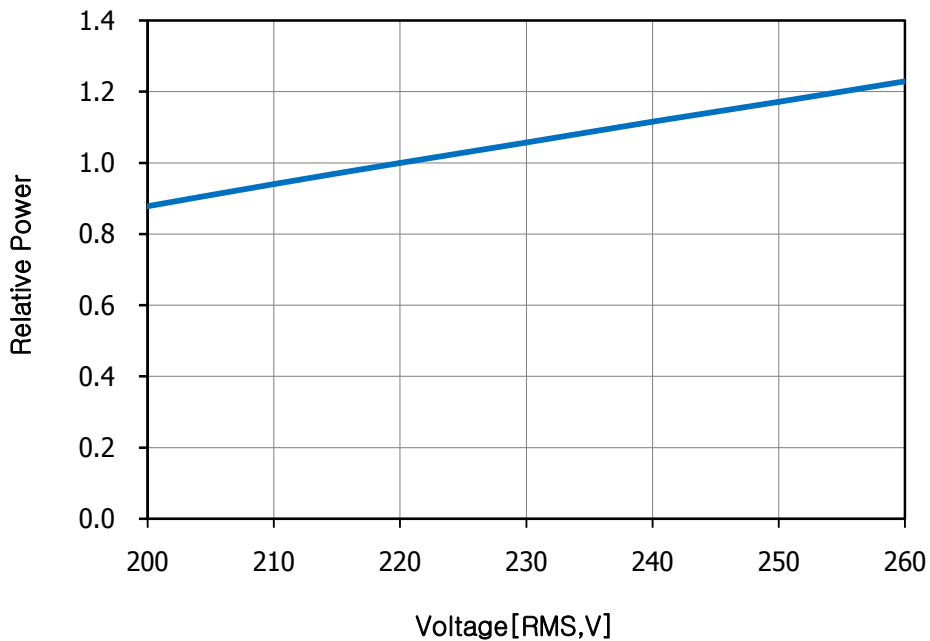
Relative Luminous Distribution

Fig 6. Relative Luminous Flux vs. Voltage at T_a=25℃, 120V
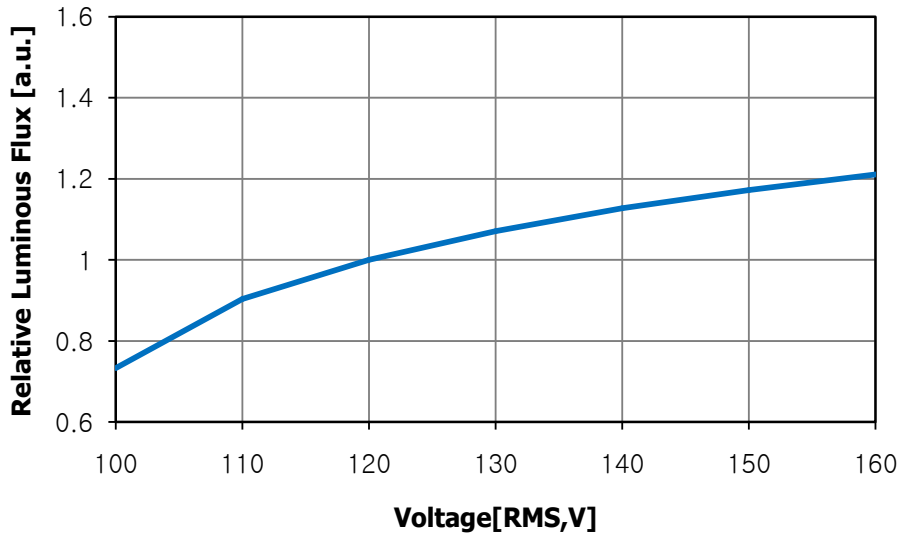
Fig 7. Relative Luminous Flux vs. Voltage at T_a=25℃, 220V

![SEOUL SEMICONDUCTOR]
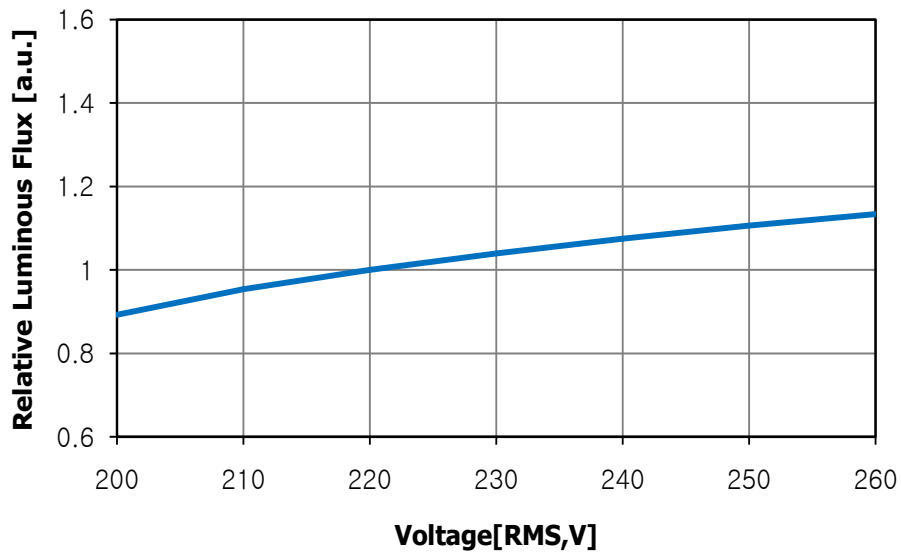
Luminous Flux Characteristics

Fig 8. Radiant Pattern, T$_a$=25℃

Color Bin Structure
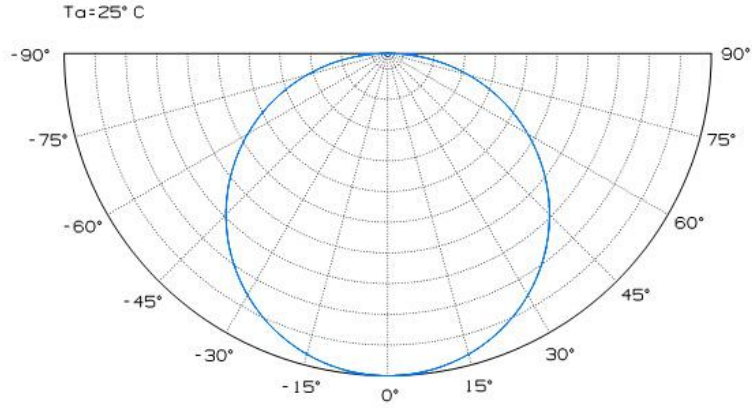
CIE Chromaticity Diagram
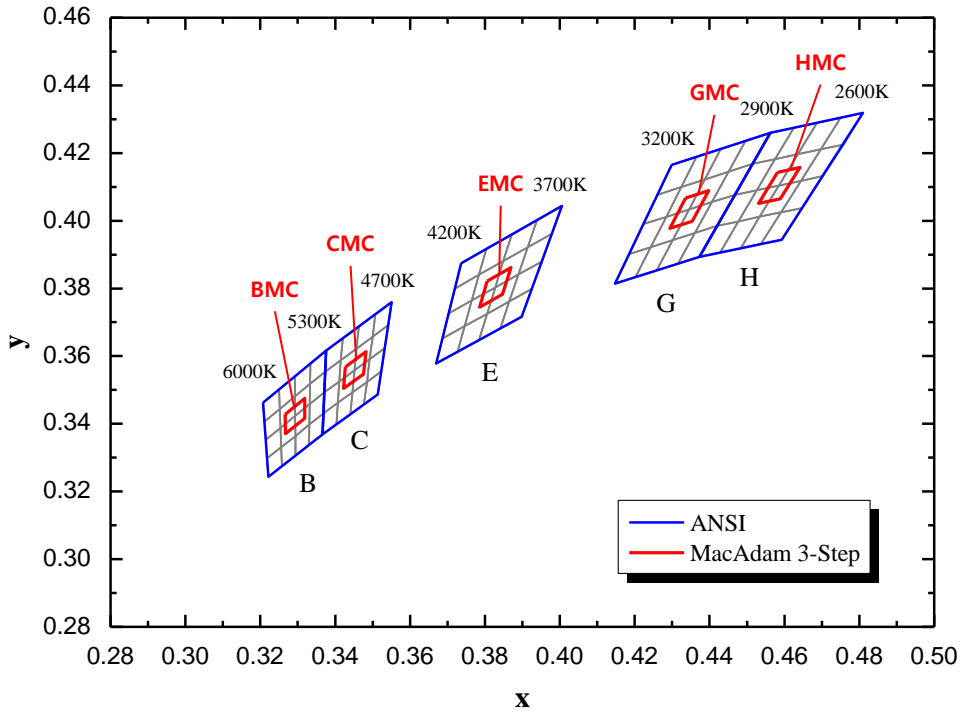
Bin	x	y	Bin	x	y	Bin	x	y
BMC	0.3266	0.3428	CMC	0.3427	0.3568	EMC	0.3806	0.3822
	0.3268	0.3371		0.3423	0.3504		0.3786	0.3745
	0.3319	0.3416		0.3476	0.3547		0.3846	0.3782
	0.3319	0.3476		0.3482	0.3613		0.3870	0.3861
GMC	0.4336	0.4067	HMC	0.4581	0.4143			
	0.4294	0.3977		0.4531	0.4051			
	0.4354	0.3999		0.4589	0.4065			
	0.4398	0.4089		0.4641	0.4157			

Color Bin Structure
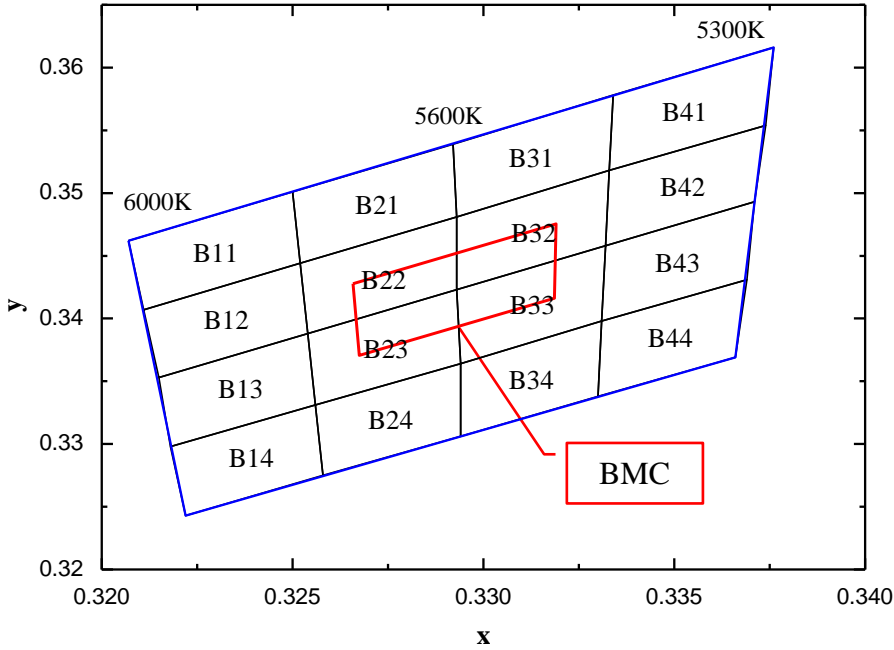
CIE Chromaticity Diagram

Bin	x	y	Bin	x	y	Bin	x	y	Bin	x	y
	0.3207	0.3462		0.3250	0.3501		0.3292	0.3539		0.3334	0.3578
B11	0.3211	0.3407	**B21**	0.3252	0.3444	**B31**	0.3293	0.3481	**B41**	0.3333	0.3518
	0.3252	0.3444		0.3293	0.3481		0.3333	0.3518		0.3374	0.3554
	0.3250	0.3501		0.3292	0.3539		0.3334	0.3578		0.3376	0.3616
	0.3211	0.3407		0.3252	0.3444		0.3293	0.3481		0.3333	0.3518
B12	0.3215	0.3353	**B22**	0.3254	0.3388	**B32**	0.3293	0.3423	**B42**	0.3332	0.3458
	0.3254	0.3388		0.3293	0.3423		0.3332	0.3458		0.3371	0.3493
	0.3252	0.3444		0.3293	0.3481		0.3333	0.3518		0.3374	0.3554
	0.3215	0.3353		0.3254	0.3388		0.3293	0.3423		0.3332	0.3458
B13	0.3218	0.3298	**B23**	0.3256	0.3331	**B33**	0.3294	0.3364	**B43**	0.3331	0.3398
	0.3256	0.3331		0.3294	0.3364		0.3331	0.3398		0.3369	0.3431
	0.3254	0.3388		0.3293	0.3423		0.3332	0.3458		0.3371	0.3493
	0.3218	0.3298		0.3256	0.3331		0.3294	0.3364		0.3331	0.3398
B14	0.3222	0.3243	**B24**	0.3258	0.3275	**B34**	0.3294	0.3306	**B44**	0.3330	0.3338
	0.3258	0.3275		0.3294	0.3306		0.3330	0.3338		0.3366	0.3369
	0.3256	0.3331		0.3294	0.3364		0.3331	0.3398		0.3369	0.3431

Color Bin Structure

CIE Chromaticity Diagram
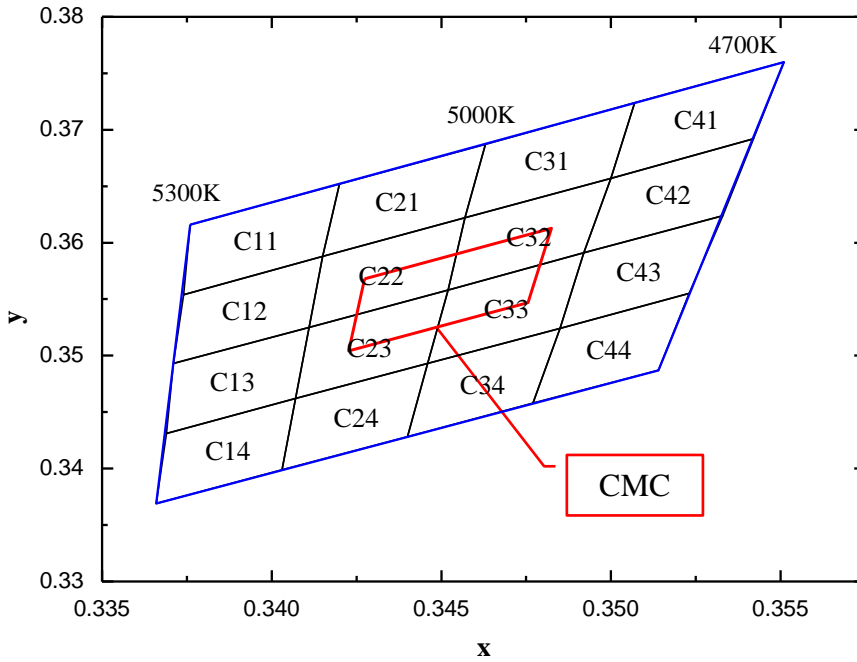
Bin	x	y	Bin	x	y	Bin	x	y	Bin	x	y
C11	0.3376	0.3616	**C21**	0.3420	0.3652	**C31**	0.3463	0.3687	**C41**	0.3507	0.3724
	0.3374	0.3554		0.3415	0.3588		0.3457	0.3622		0.3500	0.3657
	0.3415	0.3588		0.3457	0.3622		0.3500	0.3657		0.3542	0.3692
	0.3420	0.3652		0.3463	0.3687		0.3507	0.3724		0.3551	0.3760
C12	0.3374	0.3554	**C22**	0.3415	0.3588	**C32**	0.3457	0.3622	**C42**	0.3500	0.3657
	0.3371	0.3493		0.3411	0.3525		0.3452	0.3558		0.3492	0.3591
	0.3411	0.3525		0.3452	0.3558		0.3492	0.3591		0.3533	0.3624
	0.3415	0.3588		0.3457	0.3622		0.3500	0.3657		0.3542	0.3692
C13	0.3371	0.3493	**C23**	0.3411	0.3525	**C33**	0.3452	0.3558	**C43**	0.3492	0.3591
	0.3369	0.3431		0.3407	0.3462		0.3446	0.3493		0.3485	0.3524
	0.3407	0.3462		0.3446	0.3493		0.3485	0.3524		0.3523	0.3555
	0.3411	0.3525		0.3452	0.3558		0.3492	0.3591		0.3533	0.3624
C14	0.3369	0.3431	**C24**	0.3407	0.3462	**C34**	0.3446	0.3493	**C44**	0.3485	0.3524
	0.3366	0.3369		0.3403	0.3399		0.3440	0.3428		0.3477	0.3458
	0.3403	0.3399		0.3440	0.3428		0.3477	0.3458		0.3514	0.3487
	0.3407	0.3462		0.3446	0.3493		0.3485	0.3524		0.3523	0.3555

Color Bin Structure

CIE Chromaticity Diagram
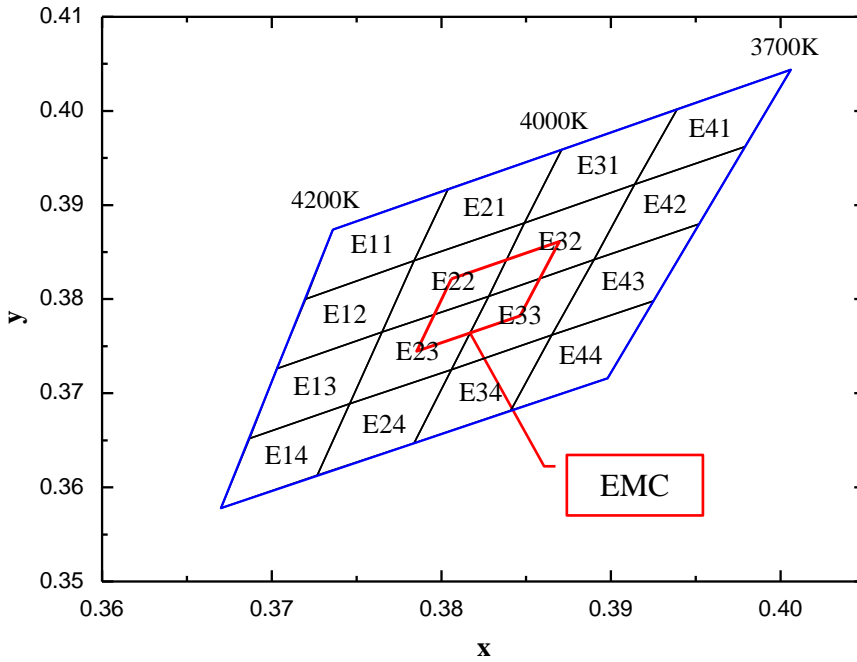
Bin	x	y	Bin	x	y	Bin	x	y	Bin	x	y
E11	0.3736	0.3874	**E21**	0.3804	0.3917	**E31**	0.3871	0.3959	**E41**	0.3939	0.4002
	0.3720	0.3800		0.3784	0.3841		0.3849	0.3881		0.3914	0.3922
	0.3784	0.3841		0.3849	0.3881		0.3914	0.3922		0.3979	0.3962
	0.3804	0.3917		0.3871	0.3959		0.3939	0.4002		0.4006	0.4044
E12	0.3720	0.3800	**E22**	0.3784	0.3841	**E32**	0.3849	0.3881	**E42**	0.3914	0.3922
	0.3703	0.3726		0.3765	0.3765		0.3828	0.3803		0.3890	0.3842
	0.3765	0.3765		0.3828	0.3803		0.3890	0.3842		0.3952	0.3880
	0.3784	0.3841		0.3849	0.3881		0.3914	0.3922		0.3979	0.3962
E13	0.3703	0.3726	**E23**	0.3765	0.3765	**E33**	0.3828	0.3803	**E43**	0.3890	0.3842
	0.3687	0.3652		0.3746	0.3689		0.3806	0.3725		0.3865	0.3762
	0.3746	0.3689		0.3806	0.3725		0.3865	0.3762		0.3925	0.3798
	0.3765	0.3765		0.3828	0.3803		0.3890	0.3842		0.3952	0.3880
E14	0.3687	0.3652	**E24**	0.3746	0.3689	**E34**	0.3806	0.3725	**E44**	0.3865	0.3762
	0.3670	0.3578		0.3727	0.3613		0.3784	0.3647		0.3841	0.3682
	0.3727	0.3613		0.3784	0.3647		0.3841	0.3682		0.3898	0.3716
	0.3746	0.3689		0.3806	0.3725		0.3865	0.3762		0.3925	0.3798

Color Bin Structure
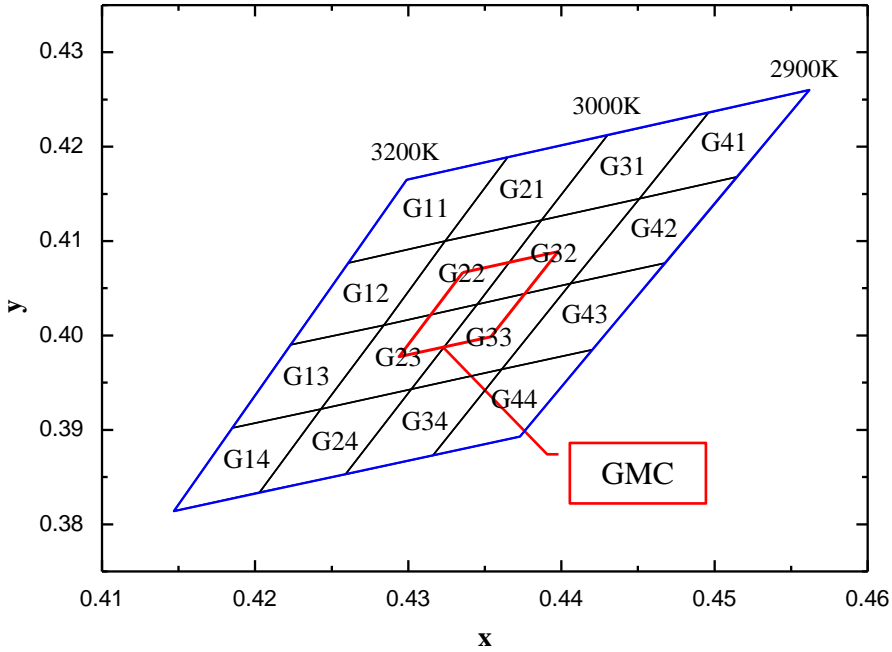
CIE Chromaticity Diagram

Bin	x	y	Bin	x	y	Bin	x	y	Bin	x	y
	0.4299	0.4165		0.4364	0.4188		0.4430	0.4212		0.4496	0.4236
	0.4261	0.4077		0.4324	0.4099		0.4387	0.4122		0.4451	0.4145
G11	0.4324	0.4100	G21	0.4387	0.4122	G31	0.4451	0.4145	G41	0.4514	0.4168
	0.4365	0.4189		0.4430	0.4212		0.4496	0.4236		0.4562	0.4260
	0.4261	0.4077		0.4324	0.4100		0.4387	0.4122		0.4451	0.4145
	0.4223	0.3990		0.4284	0.4011		0.4345	0.4033		0.4406	0.4055
G12	0.4284	0.4011	G22	0.4345	0.4033	G32	0.4406	0.4055	G42	0.4468	0.4077
	0.4324	0.4100		0.4387	0.4122		0.4451	0.4145		0.4515	0.4168
	0.4223	0.3990		0.4284	0.4011		0.4345	0.4033		0.4406	0.4055
	0.4185	0.3902		0.4243	0.3922		0.4302	0.3943		0.4361	0.3964
G13	0.4243	0.3922	G23	0.4302	0.3943	G33	0.4361	0.3964	G43	0.4420	0.3985
	0.4284	0.4011		0.4345	0.4033		0.4406	0.4055		0.4468	0.4077
	0.4243	0.3922		0.4302	0.3943		0.4302	0.3943		0.4361	0.3964
	0.4203	0.3834		0.4259	0.3853		0.4259	0.3853		0.4316	0.3873
G14	0.4147	0.3814	G24	0.4203	0.3834	G34	0.4316	0.3873	G44	0.4373	0.3893
	0.4185	0.3902		0.4243	0.3922		0.4361	0.3964		0.4420	0.3985

Color Bin Structure

CIE Chromaticity Diagram
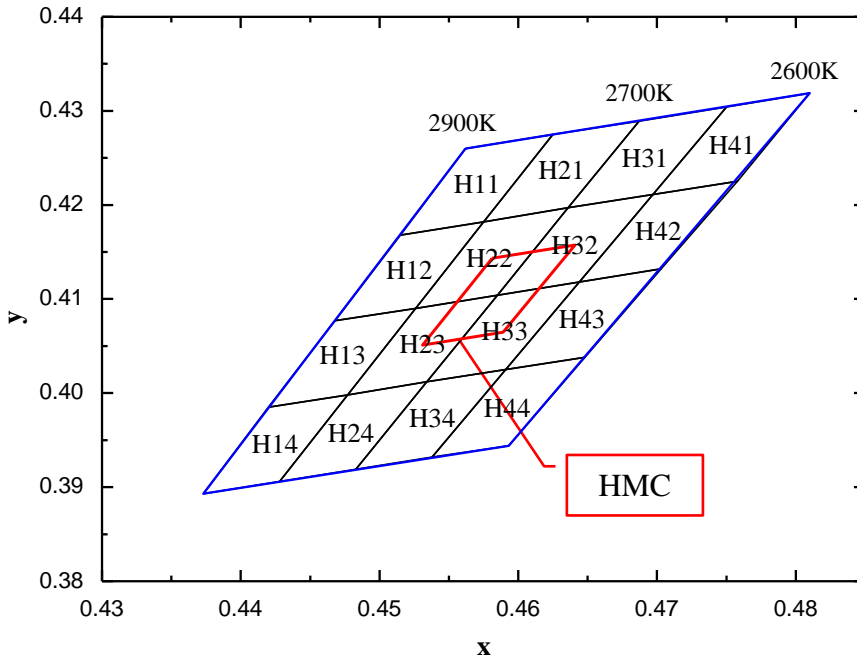
Bin	x	y	Bin	x	y	Bin	x	y	Bin	x	y
H11	0.4562	0.4260	**H21**	0.4625	0.4275	**H31**	0.4687	0.4289	**H41**	0.4750	0.4304
	0.4515	0.4168		0.4575	0.4182		0.4636	0.4197		0.4697	0.4211
	0.4575	0.4182		0.4636	0.4197		0.4697	0.4211		0.4758	0.4225
	0.4625	0.4275		0.4687	0.4289		0.4750	0.4304		0.4810	0.4319
H12	0.4515	0.4168	**H22**	0.4575	0.4182	**H32**	0.4636	0.4197	**H42**	0.4697	0.4211
	0.4468	0.4077		0.4526	0.4090		0.4585	0.4104		0.4644	0.4118
	0.4526	0.4090		0.4585	0.4104		0.4644	0.4118		0.4703	0.4132
	0.4575	0.4182		0.4636	0.4197		0.4697	0.4211		0.4758	0.4225
H13	0.4468	0.4077	**H23**	0.4526	0.4090	**H33**	0.4585	0.4104	**H43**	0.4644	0.4118
	0.4420	0.3985		0.4477	0.3998		0.4534	0.4012		0.4591	0.4025
	0.4477	0.3998		0.4534	0.4012		0.4591	0.4025		0.4648	0.4038
	0.4526	0.4090		0.4585	0.4104		0.4644	0.4118		0.4703	0.4132
H14	0.4420	0.3985	**H24**	0.4477	0.3998	**H34**	0.4534	0.4012	**H44**	0.4591	0.4025
	0.4373	0.3893		0.4428	0.3906		0.4483	0.3919		0.4538	0.3932
	0.4428	0.3906		0.4483	0.3919		0.4538	0.3932		0.4593	0.3944
	0.4477	0.3998		0.4534	0.4012		0.4591	0.4025		0.4648	0.4038

Part List

Table 5. Part List

No	Part	Reference	Specification	Quantity
1	PCB	-	Al, ø46, T=1.6, 1 layer / Cu 1oz / White PSR	1
2	LED	-	SAW8KG0B	21
3	IC	U1	MAH3082 @120Vac	1
			MAH3080 @220Vac	1

Mechanical Dimensions
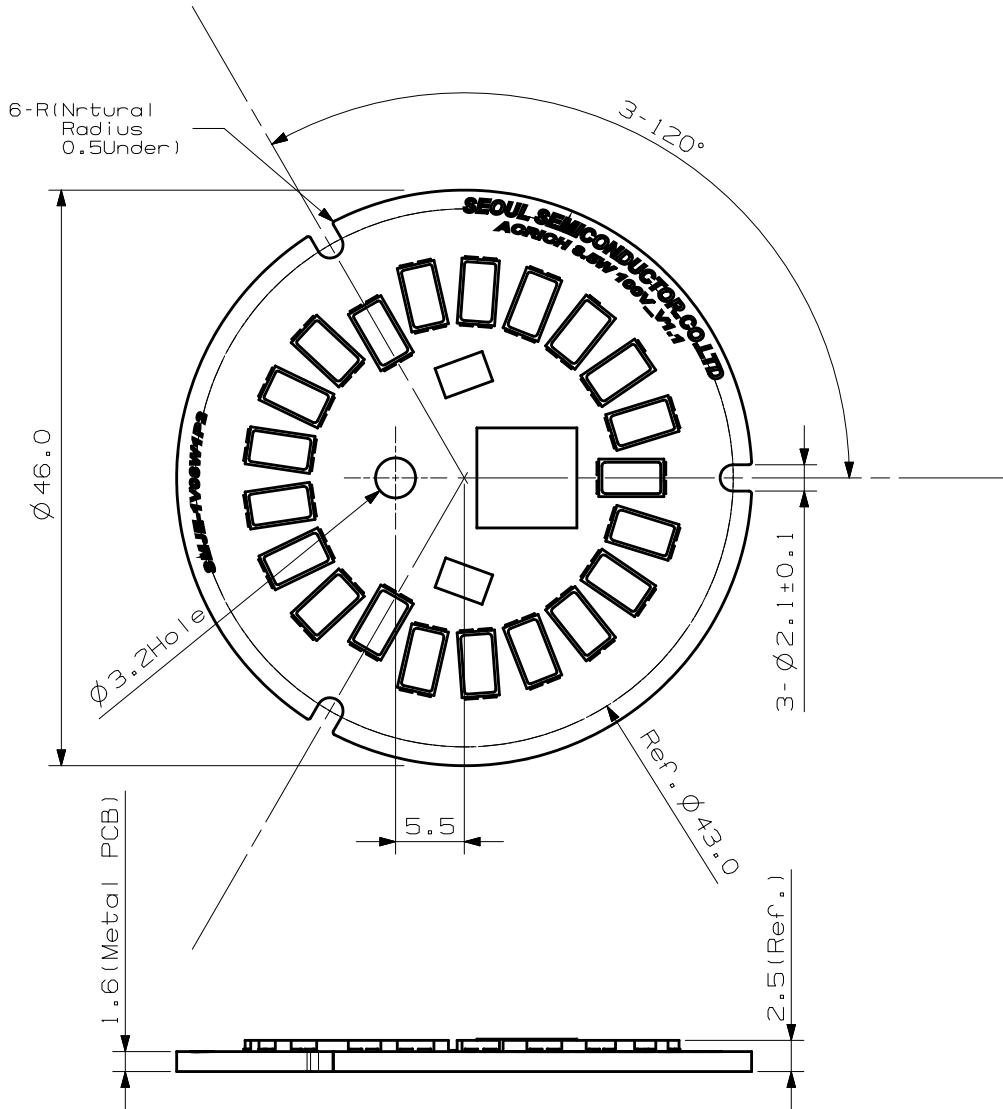
Notes :

(1) All dimensions are in millimeters. (Tolerance : ±0.2)
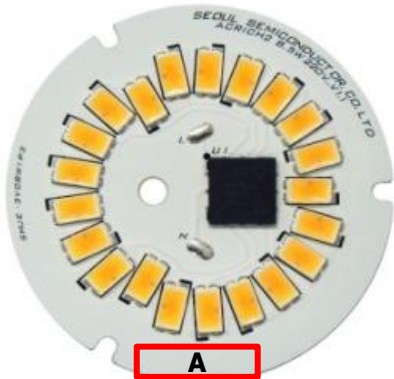
(2) Scale : None

Circuit Drawing

SMJE-2V08W1P3 (120V)
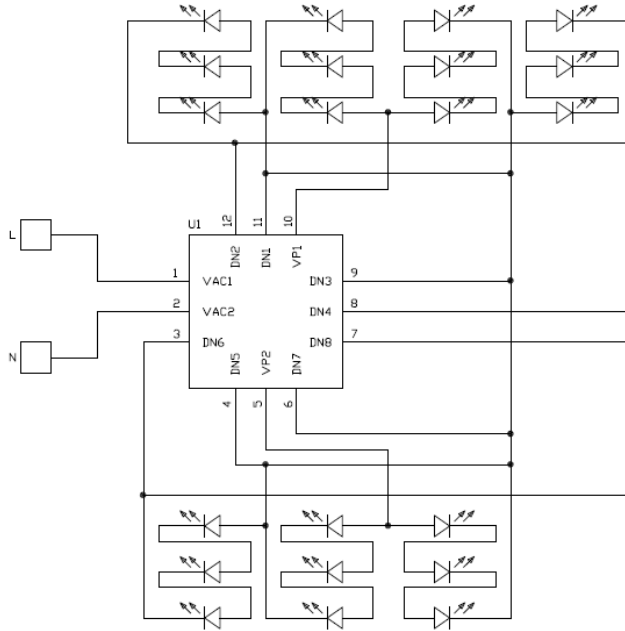
SMJE-3V08W1P3 (220V)
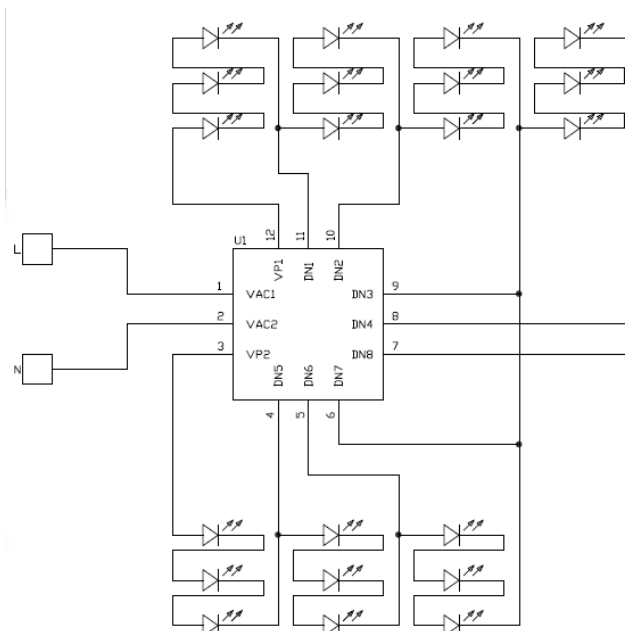
Marking Information

A : Marking

(1) Single Bin

A : ex) 140101 Z4G32

- Description

$$\underline{1\ 4\ 0\ 1\ 0\ 1}\quad \underline{Z\ 4}\ \underline{G\ 3\ 2}$$
  ①   ②   ③

① SMT Date (YYMMDD, 6 Digits)
② LED PKG. Luminous Intensity Bin (2 Digits)
③ LED PKG. Color Bin (3 Digits)

(2) Combination Bin

A : ex) 140101 08bG11

- Description

$$\underline{1\ 4\ 0\ 1\ 0\ 1}\quad 0\ 8\ b\ G\ 1\ 1$$
  ①

⑤
④
③
②

① SMT Date (YYMMDD, 6 Digits)
② Module Flux Bin (3 Digits)
③ CCT (1 Digit)
④ CCT Combination NO. (1 Digit)
⑤ VF Combination NO. (1 Digit)

② Module Flux Bin				③ CCT				④ CCT Combination			⑤ VF Combination		
Mark	Min.	Typ.	Max.	Mark	Min.	Typ.	Max.	Mark	Bin1	Bin2	Mark	Bin1	Bin2
08a	590	650	740	B	5300	5600	6000	0	22	33	1	A	A
08b	740	800	870	C	4700	5000	5300	1	23	32	2	A	B
				E	3700	4000	4200	2	33	22	3	B	A
				G	2900	3000	3200	3	32	23	4	A	C
				H	2600	2700	2900	4	MC	MC	5	C	A
											6	B	B
											7	B	C
											8	C	B
											9	C	C

SEOUL SEMICONDUCTOR

Packing

1. Tray information

- 50 PCS LED modules packed per tray

2. Tray stack and taping

5EA trays
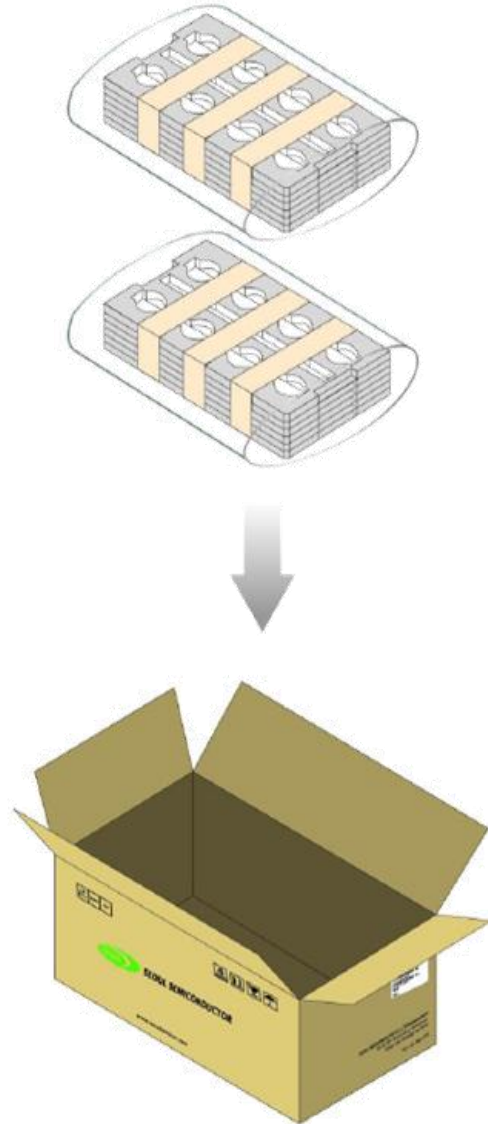with LED modules

Dummy
Tray

Taping Direction
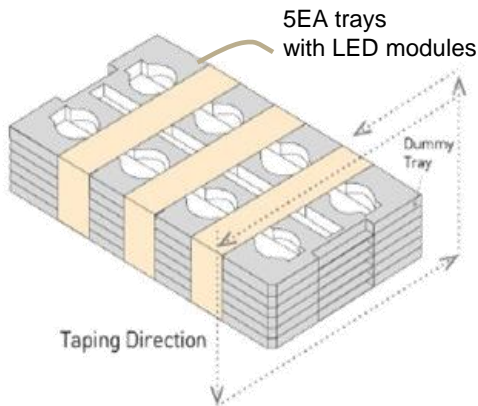
- 5 LED module trays and additional 2 dummy trays each up and down of box
- Add silica gel (1EA) on top of the tray

3. Sealing packing

Dielectric sealing pack
(700x700)
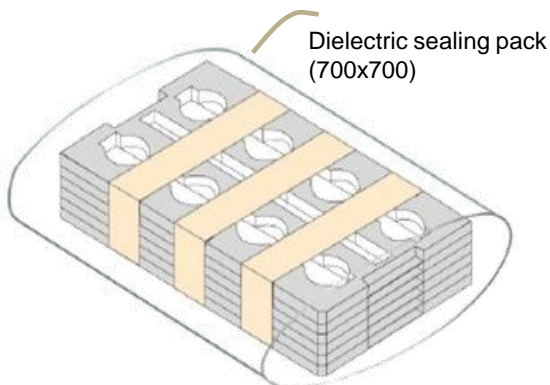
4. Box information & packing

- 500 PCS modules per BOX 1EA

** 1 Box : 50 PCS per tray x 10 trays = 500 PCS

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Label Information

| Model No.	**SMJE-XV08W1P3** (1)
Rank	**XXXXXXX** (2)
Type	**STD / 3-Step** (3)
Quantity	**XX**
Lot No.	**YYMDDXXXXX-XXXXXXX**
SEOUL	**SEOUL SEMICONDUCTOR CO.,LTD.**

Notes
(1) The model number designation is explained as follow
   SMJE : Seoul Semiconductor internal code
   XV : Input Voltage (2V = 120V, 3V = 220V)
   08W : About Power Consumption
   1 : Acrich IC Version
   P3 : MJT PKG (SAW8KG0B)
(2) It represents the LED module rank.
   ALL : Single Bin, 08a/08b : Combination Bin
   X06/X16 : Each Sub-Bin NO. (X = CCT)
   A : Single Bin, M : Combination Bin(3-Step)
(3) It represents single bin(STD) or MacAdam 3-Step(3-Step).
(4) It is attached to the top of a sealing pack & the bottom right corner of the box.

TOTAL Quantity

XX

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Notes
(1) It is attached to the bottom right corner of the box.

Handling of Silicone Resin for LEDs
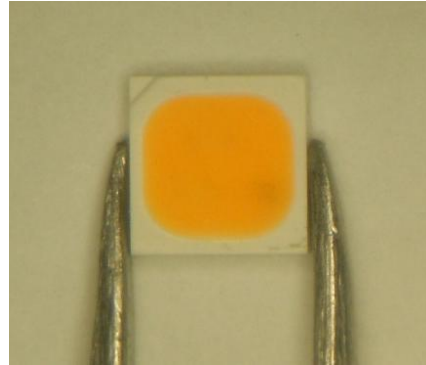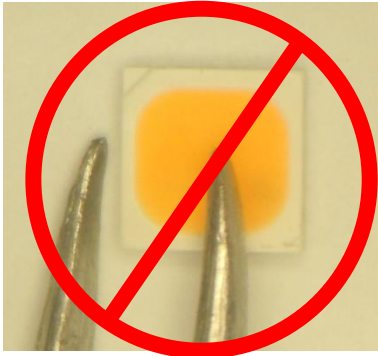
(1) Acrich2 series is encapsulated with silicone resin for high optical efficiency.

(2) Please do not touch the silicone resin area with sharp objects such as pincette(tweezers).

(3) Finger prints on silicone resin area may affect the performance.

(4) Please store LEDs in covered containers to prevent dust accumulation as this may affect performance.

(5) Excessive force more than 3000gf to the silicone lens can result in fatal or permanent damage with LEDs.

(6) Please do not cover the silicone resin area with any other resins such as epoxy, urethane, etc.

Precaution for Use

(1) Please review the Acrich2 Application Note for proper protective circuitry usage.

(2) Please note, Acrich2 products run off of high voltage, therefore caution should be taken when working near Acrich2 products.

(3) Make sure proper discharge prior to starting work.

(4) DO NOT touch any of the circuit board, components or terminals with body or metal while circuit is active.

(5) Please do not add or change wires while Acrich2 circuit is active.

(6) Long time exposure to sunlight or UV can cause the lens to discolor.

(7) Please do not use adhesives to attach the LED that outgas organic vapor.

(8) Please do not use together with the materials containing Sulfur.

(9) Please do not assemble in conditions of high moisture and/or oxidizing gas such as Cl, H_2S, NH_3, SO_2, NO_x, etc.

(10) Please do not make any modification on module.

(11) Please be cautious when soldering to board so as not to create a short between different trace patterns.

(12) Do not impact or place pressure on this product because even a small amount of pressure can damage the product. The product should also not be placed in high temperatures, high humidity or direct sunlight since the device is sensitive to these conditions.

(13) When storing devices for a long period of time before usage, please following these guidelines:
  * The devices should be stored in the anti-static bag that it was shipped in from Seoul-Semiconductor with opening.
  * If the anti-static bag has been opened, re-seal preventing air and moisture from being present in the bag.

(14) LEDs and IC are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). The Acrich2 product should also not be installed in end equipment without ESD protection. Below is a list of suggestions that Seoul Semiconductor purposes to minimize these effects.

a. ESD (Electro Static Discharge)

Electrostatic discharge (ESD) is the defined as the release of static electricity when two objects come into contact. While most ESD events are considered harmless, it can be an expensive problem in many industrial environments during production and storage. The damage from ESD to an LEDs may cause the product to demonstrate unusual characteristics such as:

Precaution for Use

- Increase in reverse leakage current lowered turn-on voltage
- Abnormal emissions from the LED at low current

The following recommendations are suggested to help minimize the potential for an ESD event.
One or more recommended work area suggestions:

- Ionizing fan setup
- ESD table/shelf mat made of conductive materials
- ESD safe storage containers

One or more personnel suggestion options:
- Antistatic wrist-strap
- Antistatic material shoes
- Antistatic clothes

Environmental controls:
- Humidity control (ESD gets worse in a dry environment)

b. EOS (Electrical Over Stress)

Electrical Over-Stress (EOS) is defined as damage that may occur when an electronic device is
subjected to a current or voltage that is beyond the maximum specification limits of the device.
The effects from an EOS event can be noticed through product performance like:

- Changes to the performance of the LED package
  (If the damage is around the bond pad area and since the package is completely encapsulated
  the package may turn on but flicker show severe performance degradation.)
- Changes to the light output of the luminaire from component failure
- Components on the board not operating at determined drive power

Failure of performance from entire fixture due to changes in circuit voltage and current across total
circuit causing trickle down failures. It is impossible to predict the failure mode of every LED exposed
to electrical overstress as the failure modes have been investigated to vary, but there are some
common signs that will indicate an EOS event has occurred:

- Damaged may be noticed to the bond wires (appearing similar to a blown fuse)
- Damage to the bond pads located on the emission surface of the LED package
  (shadowing can be noticed around the bond pads while viewing through a microscope)
- Anomalies noticed in the encapsulation and phosphor around the bond wires
- This damage usually appears due to the thermal stress produced during the EOS event

c. To help minimize the damage from an EOS event Seoul Semiconductor recommends utilizing:

- A surge protection circuit
- An appropriately rated over voltage protection device
- A current limiting device

Company Information

Published by

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Company Information

Seoul Semiconductor (www.SeoulSemicon.com) manufacturers and packages a wide selection of light emitting diodes (LEDs) for the automotive, general illumination/lighting, Home appliance, signage and back lighting markets. The company is the world's fifth largest LED supplier, holding more than 10,000 patents globally, while offering a wide range of LED technology and production capacity in areas such as "nPola", "Acrich", the world's first commercially produced AC LED, and "Acrich MJT - Multi-Junction Technology" a proprietary family of high-voltage LEDs.

The company's broad product portfolio includes a wide array of package and device choices such as Acrich and Acirch2, high-brightness LEDs, mid-power LEDs, side-view LEDs, and through-hole type LEDs as well as custom modules, displays, and sensors.

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